

requiring collector currents up to 500 mA. Sourced from Process 19.

#### **Absolute Maximum Ratings\*** TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	75	V
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V
Ic	Collector Current - Continuous	1.0	A
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	٥°

\*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

				,	continue
Electr	ical Characteristics TA =	25°C unless otherwise noted		1	1
Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHA	RACTERISTICS Collector-Emitter Breakdown Voltage*	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0	40		V
(BR)CEO (BR)CBO	Collector-Base Breakdown Voltage	$I_{\rm C} = 10 \mu{\rm A}, I_{\rm E} = 0$	75		V
	Emitter-Base Breakdown Voltage	$I_{c} = 10 \ \mu A, I_{c} = 0$ $I_{e} = 10 \ \mu A, I_{c} = 0$	6.0		V
(BR)EBO	Collector Cutoff Current	$V_{CE} = 60 \text{ V}, V_{EB(OFF)} = 3.0 \text{ V}$	0.0	10	nA
XEX	Collector Cutoff Current	$V_{CE} = 60 \text{ V}, V_{EB(OFF)} = 3.0 \text{ V}$ $V_{CB} = 60 \text{ V}, I_E = 0$		0.01	
ВО	Collector Cuton Current	$V_{CB} = 60 \text{ V}, I_E = 0$ $V_{CB} = 60 \text{ V}, I_E = 0, T_A = 150^{\circ}\text{C}$		10	μΑ μΑ
EBO	Emitter Cutoff Current	$V_{EB} = 3.0 \text{ V}, \text{ I}_{C} = 0$		10	nA
BL	Base Cutoff Current	$V_{CE}$ = 60 V, $V_{EB(OFF)}$ = 3.0 V		20	nA
	RACTERISTICS				
hfe	DC Current Gain	$ \begin{array}{l} I_{C} = 0.1 \text{ mA}, V_{CE} = 10 \text{ V} \\ I_{C} = 1.0 \text{ mA}, V_{CE} = 10 \text{ V} \\ I_{C} = 10 \text{ mA}, V_{CE} = 10 \text{ V} \\ I_{C} = 10 \text{ mA}, V_{CE} = 10 \text{ V}, T_{A} = -55^{\circ}\text{C} \\ I_{C} = 150 \text{ mA}, V_{CE} = 10 \text{ V}^{*} \\ I_{C} = 150 \text{ mA}, V_{CE} = 1.0 \text{ V}^{*} \\ I_{C} = 500 \text{ mA}, V_{CE} = 10 \text{ V}^{*} \end{array} $	35 50 75 35 100 50 40	300	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation	$I_{C} = 150 \text{ mA}, I_{B} = 15 \text{ mA}$ $I_{C} = 500 \text{ mA}, I_{B} = 50 \text{ mA}$		0.3 1.0	V V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage*	$I_{C} = 150 \text{ mA}, I_{B} = 15 \text{ mA}$ $I_{C} = 500 \text{ mA}, I_{B} = 50 \text{ mA}$	0.6	1.2 2.0	V V
		except MMPQ2222 and NMT2222)	000		
т	Current Gain - Bandwidth Product	$I_{C} = 20 \text{ mA}, V_{CE} = 20 \text{ V}, \text{ f} = 100 \text{ MHz}$	300		MHz
Cobo	Output Capacitance	$V_{CB} = 10 \text{ V}, \text{ I}_{E} = 0, \text{ f} = 100 \text{ kHz}$		8.0	pF
Cibo	Input Capacitance	$V_{EB} = 0.5 \text{ V}, I_{C} = 0, f = 100 \text{ kHz}$		25	pF
b'C <sub>C</sub>	Collector Base Time Constant	$I_{\rm C} = 20 \text{ mA}, V_{\rm CB} = 20 \text{ V}, \text{ f} = 31.8 \text{ MHz}$		150	pS
NF	Noise Figure	$I_{C} = 100 \ \mu A, V_{CE} = 10 \ V,$ $R_{S} = 1.0 \ k\Omega, f = 1.0 \ kHz$		4.0	dB
Re(h <sub>ie</sub> )	Real Part of Common-Emitter High Frequency Input Impedance	$I_{\rm C} = 20$ mA, $V_{\rm CE} = 20$ V, f = 300 MHz		60	Ω
SWITCHI		pt MMPQ2222 and NMT2222)		• •	
4	Delay Time	$V_{CC} = 30 \text{ V}, \text{ V}_{BE(OFF)} = 0.5 \text{ V},$		10	ns
r	Rise Time	$I_{\rm C} = 150 \text{ mA}, I_{\rm B1} = 15 \text{ mA}$		25	ns
6	Storage Time	$V_{\rm CC} = 30 \text{ V}, \text{ I}_{\rm C} = 150 \text{ mA},$		225	ns
3	Fall Time	$I_{B1} = I_{B2} = 15 \text{ mA}$		60	ns

# **Spice Model**

NPN (Is=14.34f Xti=3 Eg=1.11 Vaf=74.03 Bf=255.9 Ne=1.307 Ise=14.34f Ikf=.2847 Xtb=1.5 Br=6.092 Nc=2 Isc=0 Ikr=0 Rc=1 Cjc=7.306p Mjc=.3416 Vjc=.75 Fc=.5 Cje=22.01p Mje=.377 Vje=.75 Tr=46.91n Tf=411.1p Itf=.6 Vtf=1.7 Xtf=3 Rb=10)

# **NPN General Purpose Amplifier**

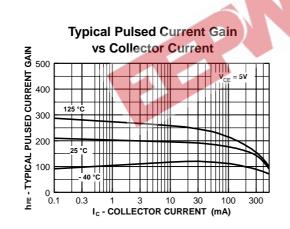
(continued)

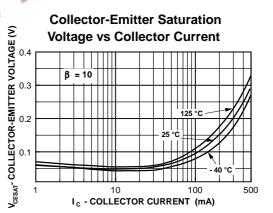
Thermal Characteristics TA = 25°C unless otherwise noted				
Symbol	Characteristic	Мах		Units
		PN2222A	*PZT2222A	
P <sub>D</sub>	Total Device Dissipation	625	1,000	mW
	Derate above 25°C	5.0	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	125	°C/W

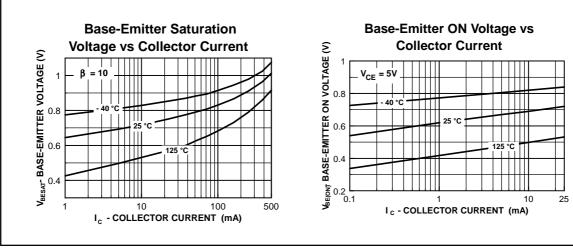
Symbol	Characteristic	Ма	Мах	
		**MMBT2222A	MMPQ2222	
P <sub>D</sub>	Total Device Dissipation	350	1,000	mW
	Derate above 25°C	2.8	8.0	mW/ºC
R <sub>eja</sub>	Thermal Resistance, Junction to Ambient	357		°C/W
	Effective 4 Die		125	°C/W
	Each Die		240	°C/W

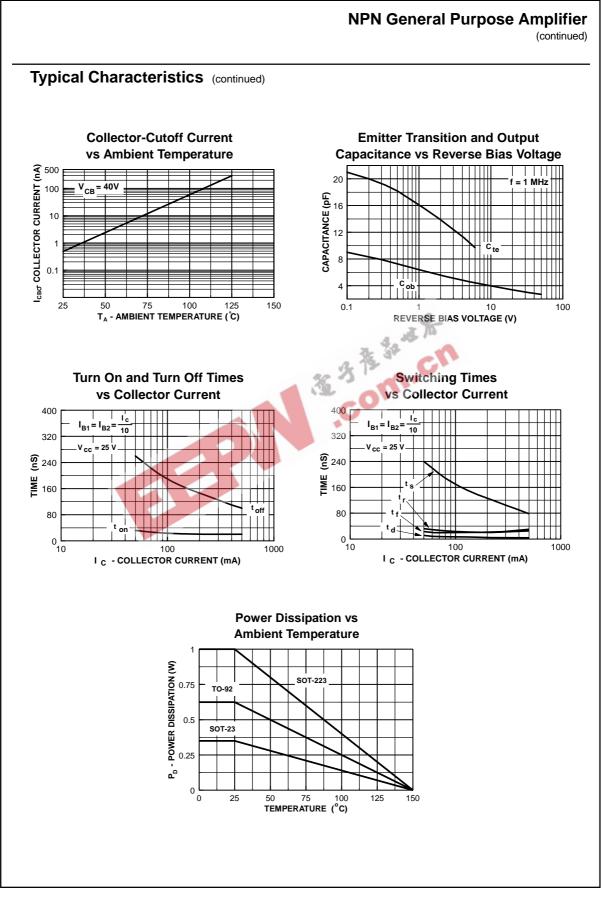
\*Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6 cm<sup>2</sup> \*\*Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06." Typical Characteristics

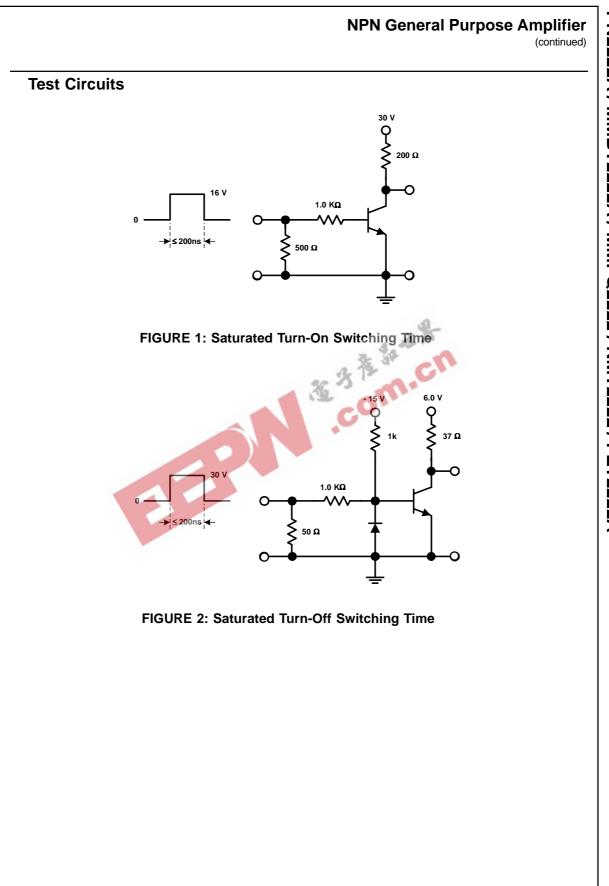
## **Typical Characteristics**











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